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(54) **SEMICONDUCTOR DEVICE AND METHODS OF FORMING THE SAME**

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(57) **ABSTRACT**

Embodiments provide a precutting technique to cut parallel openings at a front surface of a device wafer, then flipping the device wafer over and completing the cut from the back side of the device wafer to singulate a die from the wafer. The precutting technique and back side cutting technique combined provides an indentation in the side surface(s) of the device.

